

ABSTRACT OF THE DISCLOSURE

It is difficult to check the mounted state of solder by means of visual inspection after the mounting of a semiconductor device according to a conventional art, in particular, a CSP-semiconductor device, to a substrate and a problem arises wherein defective products increase and yield decreases. Terminals 50, 51, 52 and 53 for external connection are exposed from second main surface 412 of first insulating substrate 41 in the semiconductor device according to the present invention. Thus, second insulating substrate 48 is adhered to second main surface 412 so as to surround the internal portions of these terminals for external connection. Thereby, second insulating substrate 48 serves as a background mirror so that the mounted state of deep portions of the solder can be ascertained at the time of visual inspection of the mounted state of solder after the mounting of the semiconductor device to the substrate. As a result, the mounted state of the solder can be inspected without failure so that reduction in the number of defective products and increased yield can be attained.